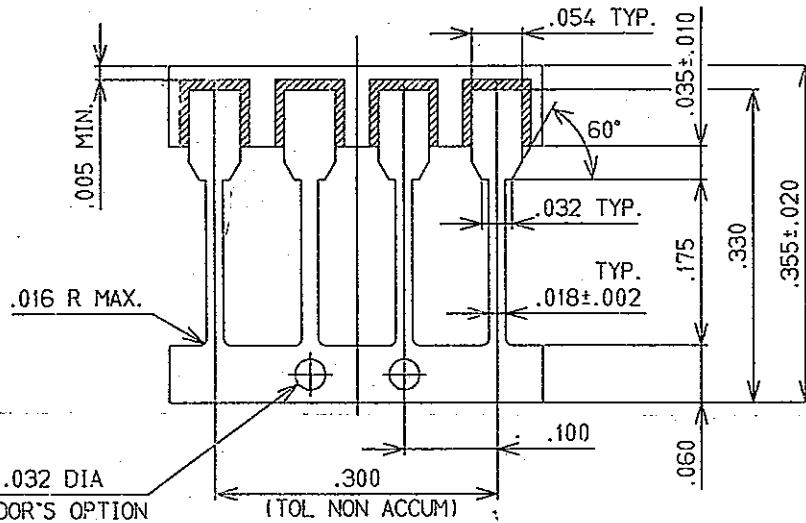
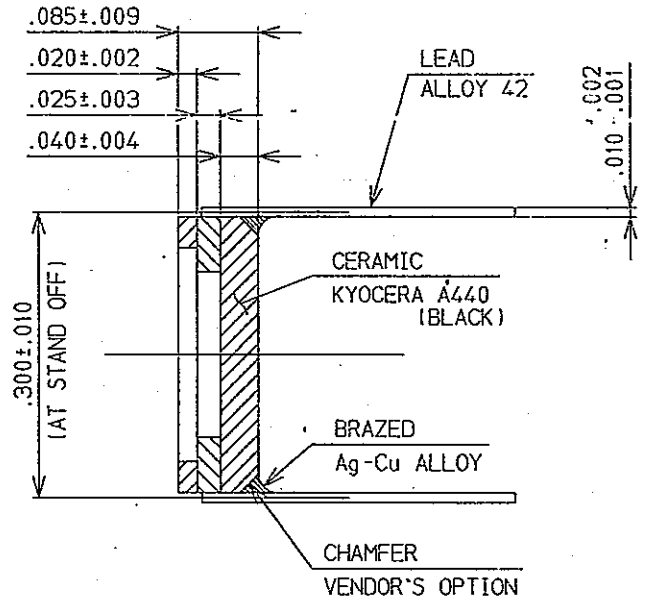
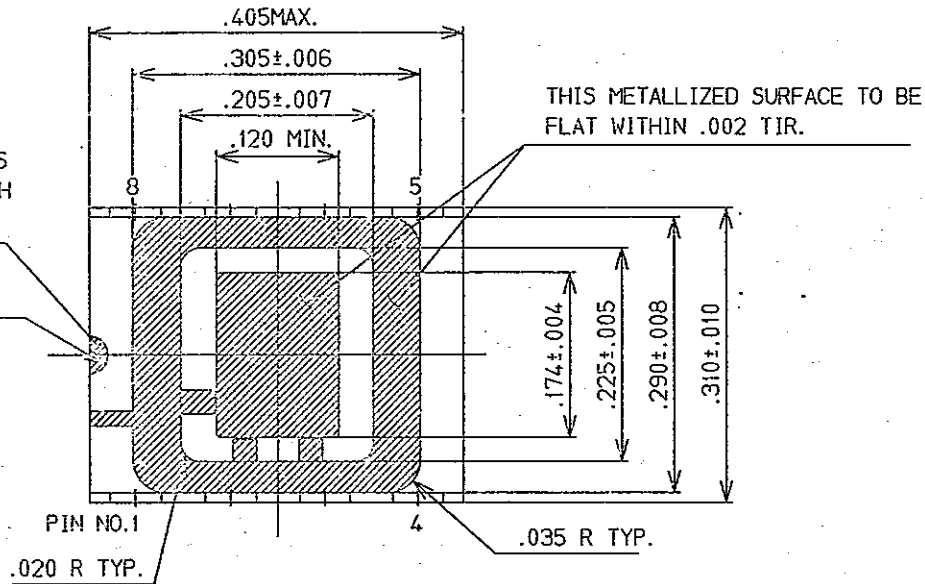


THIS METALLIZED AREA IS CONNECTED TO DIE ATTACH PAD.

.020 R NOTCH



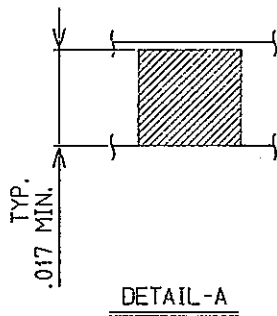
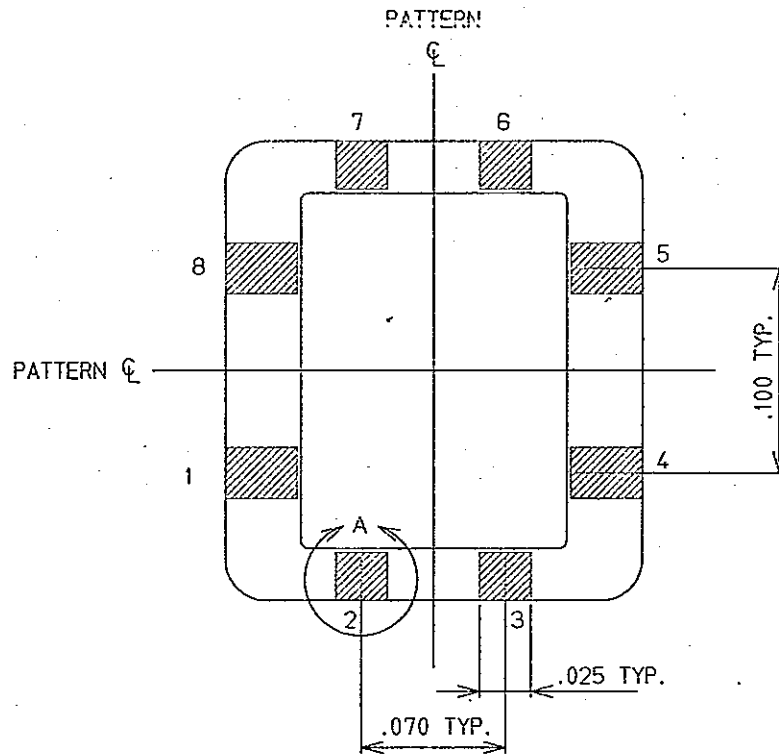
NOTES:

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE: 0.20Ω MAX.

VENDOR'S OPTION

.032 DIA VENDOR'S OPTION

MODIFICATION						NAME	TOLERANCE	SB008P832-1		S=0	D=0
						8 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
						SCALE 7/1	MATERIAL AS INDICATED	S.N	T.A		NOV.28.'84
							±.005	THIRD ANGLE PROJECTION			
	REDRAWN (CONVERTED CAD DATA)	APR.4.'85	Y.M	T.C/S.F	T.A	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		SHEET	
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			KD-84832-A	1/2		



BONDING PATTERN

MODIFICATION					NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
					8 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.N	T.A		NOV.28.'84
					SCALE 15/1	MATERIAL				
							THIRD ANGLE PROJECTION			
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN		DRAWING NO. KD-84832-A		SHEET 2/2